



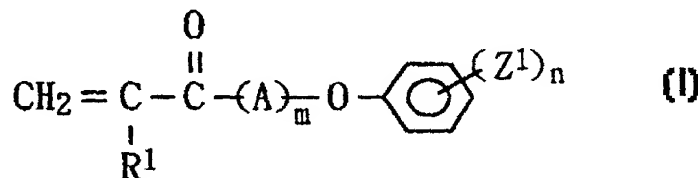
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特許協力条約に基づいて公開された国際出願

<p>(51) 国際特許分類7 G03F 7/027, C08F 20/30, 290/06, 257/00, 2/48</p>	<p>A1</p>	<p>(11) 国際公開番号 WO00/52529</p> <p>(43) 国際公開日 2000年9月8日(08.09.00)</p>
<p>(21) 国際出願番号 PCT/JP00/01221</p> <p>(22) 国際出願日 2000年3月2日(02.03.00)</p> <p>(30) 優先権データ 特願平11/55457 1999年3月3日(03.03.99) JP 特願平11/287298 1999年10月7日(07.10.99) JP</p> <p>(71) 出願人 (米国を除くすべての指定国について) 日立化成工業株式会社 (HITACHI CHEMICAL COMPANY, LTD.)[JP/JP] 〒163-0449 東京都新宿区西新宿二丁目1番1号 Tokyo, (JP)</p> <p>(72) 発明者; および (75) 発明者/出願人 (米国についてののみ) 大橋武志(OHASHI, Takeshi)[JP/JP] 石川 力(ISHIKAWA, Chikara)[JP/JP] 〒317-0061 茨城県日立市東町四丁目13番1号 日立化成工業株式会社 山崎事業所内 Ibaraki, (JP)</p> <p>(74) 代理人 弁理士 穂高哲夫(HOTAKA, Tetsuo) 〒104-0045 東京都中央区築地4-6-3-402 Tokyo, (JP)</p>		<p>(81) 指定国 AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW, 欧州特許 (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI 特許 (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG), ARIPO特許 (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), ユーラシア特許 (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM)</p> <p>添付公開書類 国際調査報告書</p>

(54) Title: PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE ELEMENT COMPRISING THE SAME, PROCESS FOR PRODUCING RESIST PATTERN, AND PROCESS FOR PRODUCING PRINTED CIRCUIT BOARD

(54) 発明の名称 感光性樹脂組成物、これを用いた感光性エメント、レジストパターン製造法及びプリント配線板の製造法

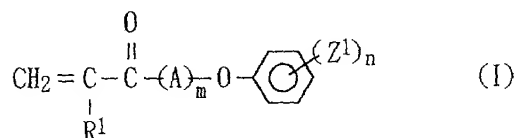


(57) Abstract

A photosensitive resin composition which comprises: (A) a carboxylated binder polymer containing comonomer units derived from styrene or a derivative thereof, (B) a photopolymerization initiator, and (C) at least one photopolymerizable compound which has at least one polymerizable, ethylenically unsaturated bond per molecule and comprises as an essential component a compound represented by general formula (I) (wherein R<sup>1</sup> represents hydrogen or methyl; A represents alkyleneoxy; Z<sup>1</sup> represents halogeno, alkyl, cycloalkyl, aryl, amino, alkylamino, dialkylamino, nitro, cyano, mercapto, alkylmercapto, allyl, hydroxyalkyl, carboxyalkyl, acyl, alkoxy, or a group containing a heterocycle; m is an integer of 4 to 20; and n is an integer of 0 to 5).

## ABSTRACT

A photosensitive resin composition comprising (A) a carboxyl group-containing binder polymer which contains styrene or a styrene derivative as a copolymerized constituent, (B) a photo-polymerization initiator, and (C) a photo-polymerizable compound which has in its molecule at least one polymerizable ethylenically unsaturated bond and comprises a compound represented by the general formula (I)



wherein  $\text{R}^1$  is a hydrogen atom or a methyl group, A is an alkyleneoxy group,  $\text{Z}^1$  is a halogen atom, an alkyl group, a cycloalkyl group, an aryl group, an amino group, an alkylamino group, a dialkylamino group, a nitro group, a cyano group, a mercapto group, an alkylmercapto group, an allyl group, a hydroxyalkyl group, a carboxyalkyl group, an acyl group, an alkoxy group or a group containing an heterocyclic group, m is an integer of 4 to 20, and n is an integer of 0 to 5.